substrate may be performed by cutting a region other than the thin-plate region on the first mother substrate.

[0040] In accordance with the fourth aspect of the invention, a method in which a plurality of input devices are formed in a lump with a large mother substrate is adopted. In this method, when cutting the first mother substrate, the thick-plate region around the thin-plate region of the substrate is cut, such that the substrate is hardly cracked. As a result, the yield can be enhanced. Moreover, when two mother substrates are different in thickness, a cutting stress is dispersed and thus cutting cannot be performed. Therefore, it is preferable that the first mother substrate and the second mother substrate substantially have the same thickness.

[0041] According to a fifth aspect of the invention, a method of manufacturing an electro-optical device which has an electro-optical panel and an input device arranged on a front surface of the electro-optical panel. Here, the input device is manufactured by the above-described method. Further, it is preferable that manufacturing the electro-optical panel includes bonding a third substrate arranged on the front surface and a fourth substrate facing the third substrate by sealing materials which are provided in ring shapes on peripheral portions of the third and fourth substrates, and sealing liquid crystal into a space surrounded by the third substrate, the fourth substrate, and the sealing materials.

[0042] In accordance with the fifth aspect of the invention, an electronic apparatus which has high durability or reliability and which is excellent in detection precision when the input is performed can be manufactured.

[0043] In accordance with the fifth aspect of the invention, the total thickness of the first substrate and the second substrate of the input device may be substantially equal to the total thickness of the third substrate and the fourth substrate of the electro-optical panel.

[0044] Since the input device has a structure in which two glass substrates are integrally bonded by the sealing material, it can be basically manufactured by the same manufacturing method as that of the liquid crystal panel. For this reason, as described above, when the total thickness of two substrates of the input device is substantially equal to the total thickness of two substrates of the liquid crystal panel, the manufacturing line of the input device can be applied to the manufacturing line of the liquid crystal panel.

[0045] In this case, the manufacturing the electro-optical panel may include forming a thin-plate region having a reduced thickness than the periphery at a position facing the coordinate input surface of the input device on a rear surface of the fourth substrate of the electro-optical panel.

[0046] As such, if the thin-plate region is formed, the fourth substrate is easily deflected. Thus, for example, when the third substrate of the liquid crystal panel is deflected by the input pressure, the fourth substrate can be deflected accordingly. For this reason, the partial change in gap can be suppressed and thus the display distortion can be prevented.

[0047] In this case, the bonding of the third substrate and the fourth substrate may include bonding a third mother substrate having a plurality of substrate regions, each serving as the third substrate, and a fourth mother substrate having a plurality of substrate regions, each serving as the fourth substrate, by the sealing materials formed on the respective substrate regions. Further, the forming of the thin-plate region on the fourth substrate may include forming the thin-plate region on a region which is the coordinate input surface of each of the substrate regions of the fourth mother substrate. At this time, the method of manufacturing an electro-optical device may further include, after the forming of the thin-plate region on the fourth substrate, cutting the bonded third and fourth mother substrates to separate electro-optical panels from each other. Here, the cutting of the fourth mother substrate may be performed by cutting a region other than the thin-plate region on the fourth mother substrate.

[0048] In accordance with the fifth aspect of the invention, a method in which a plurality of electro-optical panels are formed in a lump with a large mother substrate is adopted. In this method, when cutting the fourth mother substrate, the thick-plate region around the thin-plate region of the substrate is cut, such that the substrate is hardly cracked. As a result, the yield can be enhanced. Moreover, when two mother substrates are different in thickness, a cutting stress is dispersed and thus cutting cannot be performed. Therefore, it is preferable that the third mother substrate and the fourth mother substrate have the substantially same thickness.

BRIEF DESCRIPTION OF THE DRAWINGS

[0049] The invention will be described with reference to the accompanying drawings, wherein like numbers reference like elements, and wherein:

[0050] **FIG. 1** is a cross-sectional view showing a schematic configuration of a touch panel-integrated liquid crystal display device of the invention;

[0051] **FIG. 2** is an exploded perspective view showing a structure of a touch panel;

[0052] **FIG. 3 a** plan view of a liquid crystal panel as viewed from the touch panel;

[0053] **FIG. 4A** is a process view illustrating a method of manufacturing a liquid crystal display device of the invention;

[0054] **FIG. 4B** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;

[0055] **FIG. 4C** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;

[0056] **FIG. 4D** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;

[0057] **FIG. 5A** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;

[0058] **FIG. 5B** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;

[0059] **FIG. 5C** is a process view illustrating the method of manufacturing a liquid crystal display device of the invention;